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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicants: H. YASUYUKI, et al

Serial No.: 10/073,309

Filed: February 13, 2002

For: RESIN COMPOSITION, AND USE AND METHOD FOR PREPARING
THE SAME

Group: Not assigned

Examiner: Not assigned

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

March 18, 2002

Sir:

Prior to examination, please amend the above-identified application as follows.

IN THE CLAIMS

Please amend the claims as follows:

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1. (Amended) A resin composition comprising:
 - an epoxy resin,
 - an amine-type curing agent,
 - an organophosphorous compound having a structure represented by formula 1: